

PCN# 20131028000
Qualification of Carsem Suzhou (CSZ) as Additional Assembly and Test Site
for Select Devices on QFN/SON package
Change Notification / Sample Request

Date: 11/4/2013
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

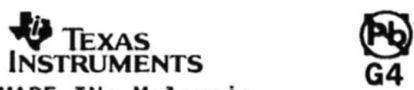

20131028000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ24210DQCR	null
TPS51200DRCT	null
BQ24072RGTT	null
BQ24075RGTT	null
BQ24210DQCT	null
BQ24313DSGT	null
BQ24314ADSGT	null
BQ24315DSGT	null
TPS2541RTET	null
TPS2560DRCT	null
TPS51200DRCR	null
TPS53311RGTT	null
TPS54319RTET	null
TPS62065DSGT	null
TPS62090RGTT	null
TPS62091RGTT	null
TPS62092RGTT	null
TPS62093RGTT	null
BQ24314DSGT	null
TPS51462RGET	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20131028000		PCN Date:	11/04/2013															
Title:	Qualification of Carsem Suzhou (CSZ) as Additional Assembly and Test Site for Select Devices on QFN/SON package																		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept: Quality Services															
Proposed 1st Ship Date:	02/04/2014	Estimated Sample Availability:	Date Provided at Sample request																
Change Type:																			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials														
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification														
<input checked="" type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process														
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process														
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process														
		<input type="checkbox"/>	Part number change																
PCN Details																			
Description of Change:																			
Qualification of Carsem Suzhou (CSZ) as Additional Assembly and Test Site for Select Devices on QFN/SON package.																			
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																			
Reason for Change:																			
Continuity of supply.																			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																			
None																			
Changes to product identification resulting from this PCN:																			
<table border="1"> <tr> <td colspan="3">Assembly Site</td> </tr> <tr> <td>UTAC Thailand</td> <td>Assembly Site Origin (22L)</td> <td>ASO: NSE</td> </tr> <tr> <td>TI Malaysia</td> <td>Assembly Site Origin (22L)</td> <td>ASO: MLA</td> </tr> <tr> <td>TI Clark - Philippines</td> <td>Assembly Site Origin (22L)</td> <td>ASO: QAB</td> </tr> <tr> <td>Carsem Suzhou</td> <td>Assembly Site Origin (22L)</td> <td>ASO: CSZ</td> </tr> </table>					Assembly Site			UTAC Thailand	Assembly Site Origin (22L)	ASO: NSE	TI Malaysia	Assembly Site Origin (22L)	ASO: MLA	TI Clark - Philippines	Assembly Site Origin (22L)	ASO: QAB	Carsem Suzhou	Assembly Site Origin (22L)	ASO: CSZ
Assembly Site																			
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TI Malaysia	Assembly Site Origin (22L)	ASO: MLA																	
TI Clark - Philippines	Assembly Site Origin (22L)	ASO: QAB																	
Carsem Suzhou	Assembly Site Origin (22L)	ASO: CSZ																	
Sample product shipping label (not actual product label)																			
  <table border="1" data-bbox="159 1467 590 1545"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> <p data-bbox="159 1545 590 1657"> OPT: ITEM: 39 LBL: 5A (L)T0:1750 </p> <p data-bbox="893 1377 1356 1646"> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS </p>					MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04											
MSL 2 / 260C / 1 YEAR	SEAL DT																		
MSL 1 / 235C / UNLIM	03/29/04																		
ASSEMBLY SITE CODES: NSE = J, TI-Malaysia = K, TI-Clark = I, Carsem Suzhou = F																			

Product Affected:

BQ24072RGTR	BQ24314ADSGT	SN1004052RTER	TPS51461RGET
BQ24072RGTRG4	BQ24314ADSGTG4	TLV62065DSGR	TPS51462RGER
BQ24072RGTT	BQ24314DSGR	TLV62065DSGT	TPS51462RGET
BQ24072RGTTG4	BQ24314DSGRG4	TPS2540ARTER	TPS53311RGTR
BQ24075RGTR	BQ24314ADSGT	TPS2540ARTET	TPS53311RGTT
BQ24075RGTRG4	BQ24314ADSGTG4	TPS2541ARTER	TPS53312RGTR
BQ24075RGTT	BQ24315DSGR	TPS2541ARTET	TPS53312RGTT
BQ24075RGTTG4	BQ24315DSGRG4	TPS2541RTER	TPS54319RTER
BQ24210DQCR	BQ24315ADSGT	TPS2541RTET	TPS54319RTET
BQ24210DQCT	BQ24315ADSGTG4	TPS2546RTER	TPS62065DSGR
BQ24300DSGR	BQ24316DSGR	TPS2546RTET	TPS62065DSGT
BQ24300DSGRG4	BQ24316DSGRG4	TPS2554DRCCR	TPS62090RGTR
BQ24300ADSGT	BQ24316ADSGT	TPS2554DRCT	TPS62090RGTT
BQ24300ADSGTG4	BQ24316ADSGTG4	TPS2560DRCCR	TPS62091RGTR
BQ24304DSGR	FX006	TPS2560DRCT	TPS62091RGTT
BQ24304DSGRG4	FX016	TPS51200DRC/2801	TPS62092RGTR
BQ24304ADSGT	HPA00512DRCCR	TPS51200DRCCR	TPS62092RGTT
BQ24304ADSGTG4	HPA00810RGTR-1/2	TPS51200DRCCR/2801	TPS62093RGTR
BQ24313DSGR	HPA00935RGTR	TPS51200DRCRG4	TPS62093RGTT
BQ24313ADSGT	HPA01187DSGR	TPS51200DRCT	
BQ24314ADSGR	SN0803054DRCCR	TPS51200DRCTG4	
BQ24314ADSGRG4	SN0803054DRCRG4	TPS51461RGER	

Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle # 1: TPA3117D2RHBR (MSL2-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	32-RHB, VQFN	Mount Compound:	SID#435143
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	12/0	12/0

Notes **- Preconditioning sequence: Level 3-260C.

Qual Vehicle #2: TPA6132A2RTER (MSL2-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	16-RTE, WQFN	Mount Compound:	SID#435933
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail	
		Lot#1	Lot#2
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	-

Notes ** - Preconditioning sequence: Level 2-260C.

Qual Vehicle # 3: TPS2540RTER (MSL2-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	16-RTE, WQFN	Mount Compound:	SID#435143
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.98 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
High Temp Life Test	125C (168 Hrs)	80/0	80/0	80/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	-

Notes ** - Preconditioning sequence: Level 2-260C.

Reference Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle # 1: 2ELVC412CDRTJR (MSL2-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	20-RTJ, WQFN	Mount Compound:	SID#435143
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-

Notes ** - Preconditioning sequence: Level 2-260C.

Qual Vehicle # 2: ONET8501PBRGTR (MSL2-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	16-RGT, VQFN	Mount Compound:	SID#435143
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-

Notes ** - Preconditioning sequence: Level 2-260C.

Qual Vehicle # 3: TPS51728RHAR (MSL3-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	20-RTJ, VQFN	Mount Compound:	SID#435143
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	76/0	75/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 3 @ 260C peak +5/-0C)	12/0	-	-

Notes ** - Preconditioning sequence: Level 3-260C.

Qual Vehicle # 4: TPS53211RGTR (MSL2-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086
# Pins-Designator, Family:	16-RGT, VQFN	Mount Compound:	SID#435143
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.0 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**Biased HAST	130C/85%RH (96hrs)	77/0	76/0	77/0
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-

Notes ** - Preconditioning sequence: Level 2-260C.

Qual Vehicle # 5: UCD9211RHAR (MSL3-260C)**Package Construction Details**

Assembly Site:	CARSEM SUZHOU	Mold Compound:	SID#441086		
# Pins-Designator, Family:	40-RHA, VQFN	Mount Compound:	SID#435143		
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size/Fail			
		Lot#1	Lot#2	Lot#3	
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Salt Atmosphere	24 hrs	22/0	22/0	22/0	
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	
Moisture Sensitivity	(level 3 @ 260C peak +5/-0C)	12/0	-	-	
Notes ** - Preconditioning sequence: Level 3-260C.					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com